Amendments to the Claims:

Pending claims 1, 2, and 12-14 have been amended. Withdrawn claims 4, 6, and 9-11 have also been amended. Claims 15-20 have been added. Please note that all claims currently pending and under consideration in the referenced application are shown below. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently amended) A method for forming an interposer substrate, comprising:
providing a rectangular, substantially planar substrate comprising a dielectric material;
forming ~~an~~ a first elongated interconnect slot and at least a second elongated interconnect slot, a longitudinal axis of the first interconnect slot and the at least a second interconnect slot positioned approximately collinear to a longitudinal centerline of the substrate, ~~comprising a plurality of longitudinally adjacent segments~~ the first interconnect slot separated by at least one transversely extending crosspiece from the at least a second interconnect slot, the first interconnect slot and the at least a second ~~elongated~~ interconnect slot being sized and configured for alignment with bond pads on a semiconductor die when the semiconductor die is placed on the substantially planar substrate, the bond pads being accessible through the interconnect slot.

2. (Currently amended) The method of claim 1, further comprising forming the first interconnect slot and the at least a second interconnect slot by milling through the substrate and the at least one transversely extending crosspiece comprises at least one unmilled portion of the substrate lying intermediate opposing, distal ends of the first interconnect slot and the at least a second elongated interconnect slot.

3. (Previously presented) The method of claim 2, further comprising producing filleted side edges on the at least one transversely extending crosspiece during the milling.

4. (Withdrawn and currently amended) The method of claim 1, wherein forming the first elongated interconnect slot and the at least a second elongated interconnect slot comprises forming a unitary elongated interconnect slot and forming the at least one transversely extending crosspiece by bonding a segment of material transversely across the unitary interconnect slot at a location intermediate opposing ends thereof.

5. (Withdrawn) The method of claim 4, wherein forming the at least one transversely extending crosspiece comprises forming a tape segment coated with an adhesive on opposing sides thereof and adhering the tape segment to a surface of the substantially planar substrate.

6. (Withdrawn and currently amended) The method of claim 1, wherein forming the first elongated interconnect slot and the at least a second elongated interconnect slot comprises forming a unitary elongated interconnect slot, forming an "I"-shaped segment of material and bonding a head portion of the "I"-shaped segment to the substrate on one side of the unitary interconnect slot and a foot portion of the "I"-shaped segment to the substrate on an opposing side of the unitary interconnect slot with a body portion of the "I"-shaped segment extending transversely thereacross to form the at least one transversely extending crosspiece.

7. (Withdrawn) The method of claim 6, further comprising forming the "I"-shaped segment as a film having an adhesive coating on opposing sides thereof.

8. (Withdrawn) The method of claim 6, further comprising forming the "I"-shaped segment as a substantially rigid plastic segment.

9. (Withdrawn and currently amended) The method of claim 1, wherein forming the first elongated interconnect slot and the at least a second elongated interconnect slot comprises forming a unitary elongated interconnect slot, forming a "T"-shaped element having a body and a cap, extending the body into the unitary interconnect slot in contact with opposing sides thereof

and bonding legs of the cap extending transversely to the unitary interconnect slot over a surface of the substrate thereto to form the at least one transversely extending crosspiece.

10. (Withdrawn and currently amended) The method of claim 1, wherein forming the first elongated interconnect slot and the at least a second elongated interconnect slot comprises forming a unitary elongated interconnect slot, forming a tape segment of a polymeric material containing a reinforcement material, disposing the tape segment transversely across the unitary interconnect slot and bonding the tape segment to a surface of the substrate.

11. (Withdrawn and currently amended) The method of claim 1, wherein forming the first elongated interconnect slot and the at least a second elongated interconnect slot comprises forming a unitary elongated interconnect slot, interposing a bar of material transversely between opposing sides of the unitary interconnect slot and bonding the bar thereto.

12. (Currently amended) The method of claim 1, further comprising forming the first elongated interconnect slot and the at least a second elongated interconnect slot to a combined length of about 67% or more of a length of the substrate.

13. (Currently amended) The method of claim 12, further comprising forming the first elongated interconnect slot and the at least a second elongated interconnect slot to a combined length of about 70 to 80% of a length of the substrate.

14. (Currently amended) The method of claim 1, further comprising locating the at least one transversely extending crosspiece substantially at a longitudinal midpoint of ~~the~~ a combined length of the first elongated interconnect slot and the at least a second elongated interconnect slot.

15. (New) A method for forming an interposer substrate, comprising:

providing a rectangular, substantially planar substrate comprising a dielectric material;

forming at least a plurality of elongated interconnect slots, a longitudinal axis of each of the at least a plurality of interconnect slots positioned approximately collinear to a longitudinal centerline of the substrate, each of the at least a plurality of interconnect slots separated by at least one of a plurality of transversely extending crosspieces from at least another of the at least a plurality of interconnect slots, the at least a plurality of interconnect slots being sized and configured for alignment with bond pads on a semiconductor die when the semiconductor die is placed on the substantially planar substrate, the bond pads being accessible through the at least a plurality of interconnect slots,

16. (New) The method of claim 15, further comprising forming the at least a plurality of elongated interconnect slots by milling approximately the same distance through the substrate to form each of the at least a plurality of elongated interconnect slots and the at least a plurality of transversely extending crosspieces comprise at least a plurality of unmilled portions of the substrate.

17. (New) The method of claim 16, further comprising producing filleted side edges on the at least a plurality of transversely extending crosspieces during the milling.

18. (New) The method of claim 15, further comprising forming the at least a plurality of elongated interconnect slots to a combined length of about 67% or more of a length of the substrate.

19. (New) The method of claim 18, further comprising forming the at least a plurality of elongated interconnect slots to a combined length of about 70 to 80% of a length of the substrate.

20. (New) The method of claim 15, further comprising locating each of the at least a plurality of transversely extending crosspieces approximately equidistant from at least a first

adjacent crosspiece and one of a second adjacent crosspiece and an end of an elongated interconnect slot.